

LISTING OF THE CLAIMS

The following listing of claims replaces all prior versions.

1. (Currently Amended) A lead frame ~~provided with~~ comprising:
a frame; ~~having a~~
first and a second connection conductors respectively ~~conductor, which~~
~~connection conductors are each~~ connected to the frame and provided with a non-engaging
end portion within a perimeter of the frame, the end portion of the second connection
conductor ~~within the frame~~ being positioned adjacent an ~~outside the~~ extension of the first
connection conductor, the second connection conductor configured ~~adapted to~~ bend
~~deform such that, by bending~~ along a bending axis which is at an oblique angle with
respect to the longitudinal axis of the end portion; to position the end portion of the
second connection conductor ~~can be positioned~~ opposite the first connection conductor to
secure, ~~and a semiconductor element can be placed~~ between said connection conductors.
2. (Currently Amended) A lead frame as claimed in claim 1, characterized in that the
end portion of the second connection conductor is positioned ~~has been brought to a~~
~~position~~ opposite the position of the semiconductor element and bent ~~by bending~~ along a
bending axis which is at an oblique angle with respect to the longitudinal axis of the end
portion.
3. (Currently Amended) A method of manufacturing a semiconductor device
comprising the steps of:
 - providing a semiconductor element having a first and a second electric
connection region which connection regions are situated at opposite sides of the
semiconductor element;
 - providing a lead frame ~~as claimed in claim 2~~ having first and second connection
conductors respectively connected to a frame and having freely-extending end portions,
the end portion of the second conductor being bent along a bending axis that is at an
oblique angle with respect to a longitudinal axis of the end portion, and extending over
the end portion of the first conductor; and

- fitting the semiconductor element between the freely-extending end portions of the first connection conductor and the second connection conductor, ~~where~~ using connection means ~~are used~~ to make electroconductive connections between the connection regions and the end portions.

4. (Currently Amended) A method of manufacturing a semiconductor device comprising the steps of:

- providing a semiconductor element having a first and a second electric connection region, which connection regions are situated on opposite sides of the semiconductor element;

- providing a lead frame having a frame with a first and a second connection conductor, which connection conductors are each connected to the frame and provided with an exposed, freely-extending end portion;

- applying the semiconductor element to the end portion of the first connection conductor, an electroconductive connection between the first connection region and the end portion being made by using a connection means;

- moving the end portion of the second connection conductor to a position outside the plane of the frame and opposite a location for the second connection region of the semiconductor element,

- making an electroconductive connection between the second connection region and the end portion of the second connection conductor by using a connection means, characterized in that the end portion of the second connection conductor within the frame is positioned outside the extension of the first connection conductor and is brought to a position opposite the position for the second connection region of the semiconductor element by bending along a bending axis which is at an oblique angle with respect to the longitudinal axis of the end portion.

5. (Previously presented) A method as claimed in claim 4, characterized in that the end of the end portion of the second connection conductor is bent through approximately 90 degrees along the bending axis out of the plane of the frame, and the end of the end portion is bent, along a further bending axis extending substantially parallel to the

bending axis and at a distance therefrom corresponding approximately to the thickness of the semiconductor element, through an angle of approximately 90 degrees to the position of the semiconductor element.

6. (Previously presented) A method as claimed in claim 5, characterized in that the end portion of the second connection conductor is bent along the further bending axis or along another bending axis in such a manner that said end portion extends obliquely in at least one direction with respect to the end portion of the first connection conductor which contains the position for the semiconductor element.

7. (Previously presented) A method as claimed in claim 4, characterized in that the semiconductor element is slid between the connection conductors after the end portion of the second connection conductor has been bent to a position opposite the location for the second connection region of the semiconductor element and opposite the end portion of the first connection conductor, the element being clamped between the connection conductors.

8. (Previously presented) A method as claimed in claim 3, characterized in that

- a lead frame is chosen in which the first connection conductor is provided with a hole at a distance from the position of the semiconductor element;
- the semiconductor element is placed on the hole and fixed by means of a suction device present below the hole, after which the semiconductor element is pushed between the connection conductors by means of a pusher member.

9. (Previously presented) A method as claimed in claim 3, characterized in that before the semiconductor element is slid between the connection conductors, the end portion of the first connection conductor is maintained in a depressed position by means of a pressure member, until the semiconductor element has been slid between the connection conductors.

10. (Currently Amended) A device for manufacturing a semiconductor device ~~carrying out a method as claimed in any one of claims 3 through 9, characterized in that~~ the device comprising ~~comprises~~:

- a transport mechanism for a lead frame with at least two freely-extending connection conductors;
- positioning means for positioning a semiconductor element;
- pusher means for pushing the semiconductor element in between the two connection conductors, of which one is bent to a position above the position of the other one; and

means for bending an end portion of at least one of the connection conductors along a bending axis which makes an oblique angle with the longitudinal axis of the end portion.

11. (Cancelled).

12. (Previously presented) A device as claimed in claim 10, characterized in that it comprises pressure means for pressing downward one of the conductor tracks, during the pushing against the semiconductor element.

13. (Currently Amended) A semiconductor device comprising:

- a semiconductor element which is provided with a first and a second electric connection region, which connection regions are situated on opposite sides of the semiconductor element;
- a first connection conductor having a contact, and facing away therefrom, an end portion which is electroconductively connected to the first connection region;
- a second connection conductor having a contact, and facing away therefrom, an end portion which is bent along a bending axis which is at an oblique angle with respect to the longitudinal axis of the end portion, such that the end portion is situated opposite the second electric connection region, with which it is electroconductively connected, while the contact is situated in the same plane as the contact of the first connection conductor, the end portion having a further bent region in contact with the second electric

connection region and having a length that corresponds approximately to the thickness of the semiconductor element; and

- an isolating envelope which leaves contacts facing way from the end portions of the connection conductors uncovered.

14. (Previously presented) A semiconductor device as claimed in claim 13, characterized in that:

- the semiconductor element is a semiconductor diode;
- the second connection conductor is u-shaped or j-shaped prior to bending,
- for the oblique angle, an angle in the range between 70 and 80 degrees is selected, and
- the contacts of the connection conductors are in line with one another.

15. (Previously presented) A semiconductor device as claimed in claim 13, characterized in that:

- the semiconductor element is a semiconductor transistor with a third connection region; and
- a third connection conductor is present, which has a contact, and facing away therefrom, an end portion which is bent along a bending axis which is at an oblique angle with respect to the longitudinal axis of the end portion, such that the end portion is situated opposite the third electric connection region, with which it is electroconductively connected, while the contact is situated in the same plane as the contact of the first connection conductor;
- the second and the third connection conductor are situated on either side of the first connection conductor.

16. (Previously presented) A semiconductor device as claimed in claim 13, or a lead frame as claimed in claim 1, characterized in that the first connection conductor is provided with a hole at a distance from the position for the semiconductor element.